EPSON

SED1575 Series

Dot Matrix LCD Driver

Support up to 65×168 Display
Built-in Power Supply Circuit for LCD

■ OVERVIEW

The 1575 series is a 1-chip dot matrix liquid crystal driver that can be connected to the bus of a microcomputer. It stores the 8-bit parallel or serial display data sent from the microcomputer in the built-in display data RAM and generates liquid crystal drive signals independently of the microcomputer. Since it incorporates 65×200 bits of the display data RAM and the one-dot pixel of the liquid crystal panel and one bit of the built-in RAM have a one-to-one correspondence, it enables display with the high degree of freedom.

The SED1575 series incorporates 65 circuits of the common output and 168 circuits of the segment output and can display 65×168 dots (capable of displaying 10 columns $\times 4$ rows of a 16×16 dot kanji font) using the single chip. The SED1577 Series incorporates 33 circuits of the common output and 200 circuits of the segment output and can display 33×200 dots (capable of displaying 12 columns $\times 2$ rows of a 16×16 dot kanji font). It can also expand the display capacity by using the two chips for the master and slave configuration.

Since the read/write operation of the display data RAM does not require external operation clocks, the SED1575 series can be operated with the minimum current consumption. Since it also incorporates a liquid crystal drive power supply with low current consumption, liquid crystal drive power supply voltage adjusting resistor, and display clock CR oscillator circuit, it can provide a display system for high performance handy equipment with the minimum current consumption and the minimum parts configuration.

■ FEATURES

Direct display of RAM data using the display data RAM

RAM bit data "1" goes on.

"0" goes off (at display normal rotation).

- RAM capacity
 65 × 200 = 13,000 bits
- Liquid crystal drive circuit
 - The SED1575 Series

65 circuits for the common output and 168 circuits for the segment output

The SED1577 Series

33 circuits for the common output and 200 circuits for the segment output

- High-speed 8-bit MPU interface (Both the 80 and 68 series MPUs can directly be connected.)/serial interface enabled
- Abundant command functions

Display Data Read/Write, Display ON/OFF, Display Normal Rotation/Reversal, Page Address Set, Display Start Line Set, column address set, Status Read, Power Supply Save Display All Lighting ON/OFF, LCD Bias Set, Read Modify Write, Segment Driver Direction Select, Electronic Control, V5 Voltage Adjusting Built-in Resistance Ratio Set, Static Indicator, n Line Alternating Current Reversal Drive, Common Output State Selection, and Built-in Oscillator Circuit ON

SED1575 Series

- Built-in static drive circuit for indicators (One set, blinking speed variable)
- Built-in power supply circuit for low power supply liquid crystal drive Booster circuit (Boosting magnification - double, triple, quadruple, boosting reference power supply external input enabled)
- 3% high accuracy alternating current voltage adjusting circuit (Temperature gradient: -0.05%/°C)
 Built-in V5 voltage adjusting resistor, built-in V1 to V4 voltage generation split resistors, built-in electronic control function, and voltage follower
- Built-in CR oscillator circuit (external clock input enabled)
- Ultra-low power consumption
- Power supplies

Logic power supply: VDD - VSS = 2.4 to 3.6 V

(SED1575Dзв, SED1577Dзв)

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VDD - VSS = 3.6 \text{ to } 5.5 \text{ V}
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(SED1575Doв, SED1577Doв)

Boosting reference power supply: VDD - VSS = 1.8 to 6.0 V

Liquid crystal drive power supply: $V_5 - V_{DD} = -4.5$ to -18.0 V (SED1575***)/-4.5 to -16.0 V (SED1577***)

- Wide operating temperature range -40 to 85°C
- CMOS process
- Shipping forms : Bare chip, TCP
- No light-resistant and radiation-resistant design are provided.

Product name	Voltage [V]	Duty	Bias	SEG Dr	COM Dr	VREG temperature gradient	Shipping form
SED1575D0B	-3.6 to -5.5	1/65	1/9, 1/7	168	65	−0.05%/°C	Bare chip
SED1575D3B	-2.4 to -3.6	1/65	1/9, 1/7	168	65	−0.05%/°C	Bare chip
SED1575T0A	-3.6 to -5.5	1/65	1/9, 1/7	168	65	−0.05%/°C	TCP
SED1575T3A	-2.4 to -3.6	1/65	1/9, 1/7	168	65	−0.05%/°C	TCP
SED1577Dob	-3.6 to -5.5	1/33	1/6, 1/5	200	33	−0.05%/°C	Bare chip
SED1577D3B	-2.4 to -3.6	1/33	1/6, 1/5	200	33	−0.05%/°C	Bare chip
SED1577T0*	-3.6 to -5.5	1/33	1/6, 1/5	200	33	−0.05%/°C	TCP
SED1577T3*	-2.4 to -3.6	1/33	1/6, 1/5	200	33	−0.05%/°C	TCP

Series Specification

SED1575 Series

BLOCK DIAGRAM



■ PIN ASSIGNMENT

Chip Specification



		Size		Unit	
	X		Y	Unit	
Chip size		13.30	×	2.81	mm
Chip thickne	SS		0.625		mm
Bump pitch			71 (Min.)		μm
Bump size	PAD No.1 to 93	85	×	85	μm
-	PAD No.94	85	×	73	μm
	PAD No.95 to 127	85	×	47	μm
	PAD No.128	85	×	73	μm
	PAD No.129	73	×	85	μm
	PAD No.130 to 301	47	×	85	μm
	PAD No.302	73	×	85	μm
	PAD No.303	86	×	73	μm
	PAD No.304 to 336	85	×	47	μm
	PAD No.337	85	×	73	μm
Bump heigh	t		17 (Typ.)		μm

■ PIN DESCRIPTION

Power Supply Pin

Pin name	I/O	Description					
Vdd	Power supply	Commonly used with the MPU power supply pin Vcc.	12				
Vss	Power supply	0 V pin connected to the system ground (GND)	9				
Vss2	Power supply	Boosting circuit reference power supply for liquid crystal drive	5				
Vrs	Power supply	External input pin for liquid crystal power supply voltage adjusting circuit They are set to OPEN	2				
V1, V2 V3, V4 V5	Power supply	Multi-level power supply for liquid crystal drive. The voltage specified according to liquid crystal cells is impedance-converted by a split resistor or operation amplifier (OP amp) and applied. The potential needs to be specified based on VDD to establish the relationship of dimensions shown below:	10				
		Master operation When the power supply is ON, the following voltages are applied to V1 ~ V4 from the built-in power supply circuit. The selection of the voltages is determined using the LCD bias set command.					
		SED1575*** SED1577***					
		V1 1/9•V5 1/7•V5 1/6•V5 1/5•V5					
		V2 Z/9•V5 Z/1•V5 Z/0•V5 Z/5•V5 V3 Z/9•V5 5/7•V5 Z/6•V5 3/5•V5					
		V4 8/9•V5 6/7•V5 5/6•V5 4/5•V5					

• LCD Power Supply Circuit Pin

Pin name	I/O	Description	Number of pins
CAP1+	0	Boosting capacitor positive side connecting pin. Connects a capacitor between the pin and CAP1– pin.	2
CAP1-	0	Boosting capacitor negative side connecting pin. Connects a capacitor between the pin and CAP1+ pin.	2
CAP2+	0	Boosting capacitor positive side connecting pin. Connects a capacitor between the pin and CAP2– pin.	2
CAP2-	0	Boosting capacitor negative side connecting pin. Connects a capacitor between the pin and CAP2+ pin.	2
CAP3-	0	Boosting capacitor negative side connecting pin. Connects a capacitor between the pin and CAP1+ pin.	2
Vout	0	Boosting output pin. Connects a capacitor between the pin and Vss2.	2
VR	I	Voltage adjusting pin. Applies voltage between VDD and V5 using a split resistor. Valid only when the V5 voltage adjusting built-in resistor is not used (IRS="L") Do not use VR when the V5 voltage adjusting built-in resistor is used (IRS="H")	1

• System Bus Connecting Pins

Pin name	I/O	Description					
D7 to D0 (SI) (SCL)	I/O	An 8-bit bidirectional data bus is used to connect an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S="L"), D7: Serial data entry pin (SI) D6: Serial clock input pin (SCL) In this case, D0 to D5 are set to high impedance. When Chip Select is in the non-active state, D0 to D7 are set to high impedance.	8				
AO	I	Normally the lowest order bit of the MPU address bus is connected to discriminate data / commands. A0="H": Indicates that D0 to D7 are display data. A0="L": Indicates that D0 to D7 are control data.	1				
RES	I	Initialized by setting RES to "L". Reset operation is performed at the RES signal level.	1				
CS1 CS2	I	Chip Select signal. When $\overline{CS1}$ ="L" and $CS2$ ="H", this signal becomes active and the input/output of data/commands is enabled.	2				
RD (E)	I	 When the 80 series MPU is connected, active "L" is set. Pin that connects the RD signal of the 80 series MPU. When this signal is "L", the SED1575 series data bus is set in the output state. When the 68 series MPU is connected, active "H" is set. 68 series MPU enable clock input pin 					
WR_ (R/W)	I	 When the 80 series MPU is connected, active "L" is set. Pin that connects the WR signal of the 80 series MPU. The data bus signal is latched on the leading edge of the WR signal. When the 68 series MPU is connected, Read/write control signal input pin R/W="H": Read operation 					
FRS	0	Output pin for static drive Used together with the SYNC pin	1				
C86	I	MPU interface switching pin C86="H": 68 series MPU interface C86="L": 80 series MPU interface	1				
P/S	I	Switching pin for parallel data entry/serial data entry P/S="H": Parallel data entry P/S="L": Serial data entry According to the P/S state, the following table is given.	1				
		P/S Data/ Data Read/write Serial clock command					
		"H" A0 D0 to D7 RD, WR					
		"L" A0 SI (D7) Write-only SCL (D6)					
	When P/S="L", D0 to D5 are set to high impedance. D0 to D5 can be "H", "L", or "OPEN". RD(E) and WR (R/W) are fixed to "H" or "L". For the serial data entry, RAM display data cannot be read.						

Pin name	I/O	Description						
CLS	I	Pin that selects the validity/invalidity of the built-in oscillator circuit for display clocks. CLS="H": Built-in oscillator circuit valid CLS="L": Built-in oscillator circuit invalid (external input) When CLS="L", display clocks are input from the CL pin. When the SED1575 series is used for the master/slave configuration, each of the CLS pins is set to the same level together. Display clock Master Slave Built-in oscillator circuit used "H" "H"						
M/S	I	Pin that selects the master/slave operation for the SED1575 series. The liquid crystal display system is synchronized by outputting the timing signal required for the liquid crystal display for the master operation and inputting the timing signal required for the liquid crystal display for the slave operation. M/S="H": Master operation M/S="L": Slave operation According to the M/S and CLS states, the following table is given. M/S CLS Oscillator Power supply CL FR SYNC FRS DOF	1					
		"H""CircuitCircuit"H""H"ValidValidOutputOutputOutput"L"InvalidValidInputOutputOutputOutput"L""H"InvalidInvalidInputInputInput"L""H"InvalidInvalidInputInputInput"L""H"InvalidInvalidInputInputInput"L""H"InvalidInvalidInputInputInput						
CL	I/O	Display clock I/O pin According to the M/S and CLS states, the following table is given. <u>M/S CLS CL</u> <u>"H" "H" Output</u> <u>"L" Input</u> <u>"L" "H" Input</u> When the SED1575 series is used for the master/slave configuration, each CL pin is connected.	1					
FR	I/O	Liquid crystal alternating current signal I/O pin M/S="H": Output M/S="L": Input When the SED1575 series is used for the master/slave configuration, each FR pin is connected.	1					
SYNC	I/O	Liquid crystal synchronizing current signal I/O pin M/S="H": Output M/S="L": Input When the SED1575 series is used for the master/slave configuration, each SYNC pin is connected.	2					
DOF	I/O	Liquid crystal display blanking control pin M/S="H": Output M/S="L": Input <u>When</u> the SED1575 series is used for the master/slave configuration, each DOE pin is connected.						
IRS	I	V5 voltage adjusting resistor selection pin IRS="H": Built-in resistor used IRS="L": Built-in resistor not used. The V5 voltage is adjusted by the VR pin and stand-alone split resistor. Valid only at master operation. The pin is fixed to "H" or "L" at slave operation.	1					
НРМ	I	Power supply control pin of the power supply circuit for liquid crystal drive <u>HPM</u> ="H": Normal mode HPM="L": High power supply mode Valid only at master operation. The pin is fixed to "H" or "L" at slave operation.	1					

Liquid Crystal Drive Pin

Pin name	I/O	Description						
SEG0 to	0	Output pins for the For the pin assignment	CD segn	nent drive. odel, refer to the table	e below.		168 or 200	
SEGN		Product	name	SEG	Number of pins]		
		SED157	5* _{**}	SEG0 to SEG167	168			
		SED157	7* _{**}	SEG0 to SEG199	200			
		Contents of the disp level among VDD, V	lay RAM 2, V3 and	and FR signal are co V5.	ombined to select a d	esired		
				Outpu	ut voltage			
		RAM data	FR	Display normal operation	Display reversal			
		Н	Н	Vdd	V2			
		Н	L	V5	V3			
		L	Н	V2	Vdd			
		L	L	V3	V5	-		
		Power save	» —		Vdd			
COM0 to		Output pins for the LCD common drive. For the pin assignment by model, refer to the table below.						
COlvin		Product	name	SEG	Number of pins]		
		SED157	5* _{**}	COM0 to COM63	64			
		SED157	7* _{**}	COM0 to COM31	32			
		Scan data and FR s V1, V4 and V5.	ignal are	combined to select a	i desired level among	j Vdd,		
		Scanning	g data	FR	Output voltage			
		Н		Н	V5			
		Н		L	Vdd			
		L		Н	V1			
		L		L	V4			
		Powers	save	—	Vdd			
COMS	0	Indicator dedicated Set to OPEN when When COMS is use to both the master a	COM out not used d for the i	put pin master/slave configu	ration, the same sign	al is output	2	

• Test Pin

Pin name	I/O	Description	Number of pins
TEST1 to 6	I/O	IC chip test pin. Fix the pin to "H".	6
TEST7 to 9	I/O	IC chip test pin. Take into consideration so that the capacity of lines cannot be exhausted by setting the pin to OPEN.	3

■ ABSOLUTE MAXIMUM RATINGS

			V	ss=0∖	/ unless spec	ified otherwise
Item	Symbol	Specif	Specification value			
Power supply voltage		Vdd	-0.3	to	+7.0	V
Power supply voltage (2)			-7.0	to	+0.3	
(Based on VDD)	At triple boosting	Vss2	-6.0	to	+0.3	
	At quadruple boosting		-4.5	to	+0.3	
Power supply voltage (3) (Bas	V5, Vout	-20.0	to	+0.3		
Power supply voltage (4) (Bas	sed on VDD)	V1, V2, V3, V4	V5	to	+0.3	
Input voltage		VIN	-0.3	to	Vdd+0.3	
Output voltage		Vout	-0.3	to	Vdd+0.3	
Operating temperature	TOPR	-40	to	+85	°C	
Storage temperature	ТСР	TSTR	-55	to	+100	
	Bare chip		-55	to	+125	



Notes: 1. The values of the Vss2, V1 to V5, and V0 voltages are based on VDD=0 V.

- 2. The V1, V2, V3, and V4 voltages must always satisfy the condition of $VDD \ge V1 \ge V2 \ge V3 \ge V4 \ge V5$. 3. When LSI is used exceeding the absolute maximum ratings, the LSI may be damaged permanently. Besides, it is desirable that the LSI should be used in the electrical characteristics condition for normal operation. If this condition is exceeded, the LSI may malfunction and have an adverse effect on the reliability of the LSI.

■ DC CHARACTERISTICS

Unless otherwise specified, Vss=0 V, Ta=-40 to $85^{\circ}C$

14	om	Symbol	Condition		Spe	cification	value	Unit	Applicable
	em	Symbol			Min.	Тур.	Max.	Unit	pin
Operating vo	ltage (1)	Vdd	SED1575*3*/SED15	577*3*	2.4		3.6	V	Vdd
		Vdd	SED1575*0*/SED15	5 77 *0*	3.6	—	5.5		Vdd
Operating vo	ltage (2)	VSS2	(Based on VDD)		-6.0	_	-1.8		Vss2
Operating vo	ltage (3)	V5	SED1575*** (Based	d on Vdd)	-18.0		-4.5		V5
		V5	SED1577*** (Based	d on Vdd)	-16.0	—	-4.5		V5
		V1, V2	(Based on VDD)		0.4×V5	_	Vdd		V1, V2
		V3, V4	(Based on VDD)		V5	—	0.6×V5		V3, V4
High level inp	out voltage	VIHC			0.8×Vdd		Vdd		
Low level inp	nput voltage VILC		Vss	—	0.2×Vdd				
High level ou	tput voltage	Vонс	Іон=–0.5mA		0.8×Vdd		Vdd		
Low level out	put voltage	Volc	IoL=0.5mA		Vss	_	0.2×Vdd		
Input leak cu	rrent	lu	VIN=VDD or Vss		-1.0		1.0	μA	
Output leak c	urrent	Ilo			-3.0		3.0		
Liquid crystal	driver	Ron	Ta=25°C	V5=-14.0V	—	2.0	3.5	KΩ	SEGn
On resista	ince		(Based on VDD)	V5=-8.0V	_	3.2	5.4		COMn
Static current	consumption	Issq			—	0.01	5	μΑ	Vss, Vss2
Output leak current		l5Q	V5=-18.0V (Based of	on Voo)	—	0.01	15		V5
Input pin capacity		CIN	Ta=25°C, f=1MHz		-	5.0	8.0	pF	
Oscillating	Built-in	fosc	Ta=25°C		18	22	26	kHz	
frequency	oscillation								
	External input	fc∟			4.5	5.5	6.5		CL

Item			Conc	lition	Specification value				Applicable
			Conc		Min.	Тур.	Max.	Unit	pin
ıit.	Input voltage	VSS2	At triple boosting		-6.0	-	-1.8	V	Vss2
l D			(Based on VDD)						
0 >		Vss2	At quadruple boostir	ng	-4.5	—	-1.8		Vss2
ď.	(Based on VDD)								
Ins	Boosting output voltage	Vout	(Based on VDD)		-20.0				Vout
/er	Voltage adjusting circuit	Vout	(Based on VDD)		-20.0		-6.0		Vout
NO NO	operating voltage								
in p	V/F circuit operating	V5	SED1575*** (Based on VDD)		-18.0	_	-4.5		V5
uilt-	voltage	V5	SED1577*** (Based on VDD)		-16.0	—	-4.5		V5
B	Reference voltage	VREG0	Ta=25°C,	–0.05%/°C	-2.04	-2.10	-2.16		

■ TIMING CHARACTERISTICS

• System bus read/write characteristics 1 (80 series MPU)



Re u	0.00	Symbol		Specifica	tion value	l l mit
Item	Signal	Symbol	Condition	Min.	Max.	Unit
Address hold time	A0	tAH8		0	_	ns
Address setup time		tAW8		0		
System cycle time		tCYC8		250	—	
Control L pulse width (WR)	WR	tCCLW		30	—	
Control L pulse width (RD)	RD	tCCLR		70	_	
Control H pulse width (WR)	WR	tCCHW		30	_	
Control H pulse width (RD)	RD	t CCHR		30	—	
Data setup time	D0 to D7	tDS8		30	_	
Data hold time		tDH8		10		
RD access time		tACC8	CL=100pF		70	
Output disable time		tOH8		5	50	



• System bus read/write characteristics 2 (68 series MPU)

[SED1575*0*, SED1577*0*: VDD=4.5V to 5.5V, Ta=-40 to 85°C]

lto m			Symbol	•	Specification	on value	11
Item		Signal	Symbol	Condition	Min.	Max.	Unit
Address hold time		A0	tah6		0		ns
Address setup time			tAW6		0	—	
System cycle time			tCYC6		250		
Data setup time		D0 to D7	tDS6		30	—	
Data hold time			tDH6		10	—	
Access time			tACC6	CL=100pF		70	
Output disable time			tOH6		5	50	
Enable H pulse width	Read	E	tewhr		70		
	Write		t EWHW		30	—	
Enable L pulse width	Read	E	tewlr		30		
	Write		tewlw		30	—	

[SED1575*0*, SED1577*0*: VDD=3.6V to 4.5V, Ta=-40 to 85°C]

					Specification value		
Item		Signal	Symbol	Condition	Min.	Max.	Unit
Address hold time		A0	tAH6		0	—	ns
Address setup time			tAW6		0	_	
System cycle time			tCYC6		300	—	
Data setup time		D0 to D7	tDS6		40	—	
Data hold time			tDH6		15	_	
Access time		-	tACC6	CL=100pF	_	140	
Output disable time			tOH6		10	100	
Enable H pulse width	Read	E	tewhr		120	—	
	Write		tewhw		60	_	
Enable L pulse width	Read	E	tewlr		60	—	1
	Write		tewlw		60	—	

[SED1575*3*, SED1577*3*: VDD=2.4V to 3.6V, Ta=-40 to 85°C]

		Cirmel	Cumb al	bol Condition	Specificat	tion value	Unit
Item		Signai	Symbol	Condition	Min.	Max.	Unit
Address hold time		A0	tah6		0	—	ns
Address setup time			tAW6		0	—	
System cycle time			tCYC6		800		
Data setup time		D0 to D7	tDS6		80		
Data hold time			tDH6		30		
Access time			tACC6	C∟=100pF	—	280	
Output disable time			tOH6		10	200	
Enable H pulse width	Read	E	tewhr		240		
	Write		tewhw		120		
Enable L pulse width	Read	E	tewlr		120	—	
	Write		t EWLW		120	—	

Notes: 1. The rise and fall times (tr and tr) of the input signal are specified for less than 15 ns. When using the system cycle time at high speed, they are specified for (tr+tr) ≤ (tCYC6-tEWLW-tEWHW) or (tr+tr) ≤ (tCYC6-tEWLR-tEWHR).
2. All timings are specified based on the 20 and 80% of VDD.

3. tEWLW and tEWLR are specified for the overlap period when $\overline{CS1}$ is at "L" (CS2= "H") level and E is at the "H" level.

• Serial interface



[SED1575*0*, SED1577*0*: VDD=4.5V to 5.5V, Ta=-40 to 85°C]

ltem	Cinnal	Symbol	Condition	Specifica	tion value	Unit
item	Signal	Symbol	Condition	Min.	Max.	
Serial clock cycle	SCL	tSCYC		200		ns
SCL "H" pulse width		tSHW		75		
SCL "L" pulse width		tsLw		75	—	
Address setup time	A0	tSAS		50	—	
Address hold time		t SAH		100	—	
Data setup time	SI	tSDS		50		
Data hold time		t SDH		50		
CS-SCL time	CS	tcss		100		
		tCSH		100		

ltem	Cianal	Symbol	Condition	Specificat	tion value	Unit
item	Signai		Condition	Min.	Max.	
Serial clock cycle	SCL	tSCYC		250	—	ns
SCL "H" pulse width		tSHW		100		
SCL "L" pulse width		tslw		100	—	
Address setup time	A0	tsas		150		
Address hold time		t SAH		150	—	
Data setup time	SI	tsds		100	—	
Data hold time		t SDH		100	—	
CS-SCL time	CS	tCSS		150	—	
		t CSH		150		

[SED1575*0*, SED1577*0*: VDD=3.6V to 4.5V, Ta=-40 to 85°C]

[SED1575*3*, SED1577*3*: VDD=2.4V to 3.6V, Ta=-40 to 85°C]

ltom	Cianal	Symbol	Condition	Specificat	tion value	Unit	
Item	Signal	Symbol	Condition	Min.	Max.	Unit	
Serial clock cycle	SCL	tSCYC		400	—	ns	
SCL "H" pulse width		tshw		150	—		
SCL "L" pulse width		tsLw		150	—		
Address setup time	A0	tSAS		250	—		
Address hold time		t SAH		250	—		
Data setup time	SI	tSDS		150	—		
Data hold time		t SDH		150	—		
CS-SCL time	CS	tCSS		250	_		
		tCSH		250	—		

Notes: 1. The rise and fall times (tr and tr) of the input signal are specified for less than 15 ns. 2. All timings are specified based on the 20 and 80% of VDD.

Display control output timing



[SED1575*0*, SED1577*0*: VDD=4.5V to 5.5V, Ta=-40 to 85°C]

	0.1	•		Spe	cification v	alue	
Item	Signal	Symbol	Condition	Min.	Тур.	Max.	Unit
FR delay time	FR	tDFR	C∟=50pF	—	10	40	ns
SYNC delay time	SYNC	t DSNC	C∟=50pF	—	10	40	ns

[SED1575*0*, SED1577*0*: VDD=3.6V to 4.5V, Ta=-40 to 85°C]

M a	Olama I	Quarter at	O an all the m	Spe	11		
Item	Signal Symbol Condition		Min.	Тур.	Max.	Unit	
FR delay time	FR	tDFR	CL=50pF	—	20	80	ns
SYNC delay time	SYNC	t DSNC	C∟=50pF		20	80	ns

	Signal Symbol Conditio			Spe			
Item			Condition	Min.	Тур.	Max.	Unit
FR delay time	FR	tDFR	CL=50pF	—	50	200	ns
SYNC delay time	SYNC	t DSNC	C∟=50pF	—	50	200	ns

Notes: 1. Valid only when the master mode is selected.

2. All timings are specified based on the 20 and 80% of VDD.

3. Pay attention not to cause delays of the timing signals CL, FR and SYNC to the salve side by wiring resistance, etc., while master/slave operations are in progress. If these delays occur, indication failures such as flickering may occur.

Reset input timing



[SED1575*0*, SED1577*0*: VDD=4.5V to 5.5V, Ta=-40 to 85°C]

			Spe				
Item	Signal	Symbol	Condition	Min.	Тур.	Max.	Unit
Reset time		tR		—		0.5	μs
Reset "L" pulse width	RES	trw		0.5	_	—	

[SED1575*0*, SED1577*0*: VDD=3.6V to 4.5V, Ta=-40 to 85°C]

	Signal	Symbol	Condition	Specification value			
Item				Min.	Тур.	Max.	Unit
Reset time		tR		—	—	1	μs
Reset "L" pulse width	RES	trw		1	—	—	

[SED1575*3*, SED1577*3*: VDD=2.4V to 3.6V, Ta=-40 to 85°C]

			0	Specification value			
Item	Signal	Symbol	Condition	Min.	Тур.	Max.	Unit
Reset time		tR		—	—	1.5	μs
Reset "L" pulse width	RES	trw		1.5	—	—	

Note: All timings are specified based on the 20 and 80% of VDD.

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